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(54) **LIGHT EMITTING DIODE PACKAGE**

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Jul. 14, 2014, now Pat. No. 9,059,386, which is a
continuation of application No. 13/113,662, filed on
May 23, 2011, now Pat. No. 8,796,710.

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H01L 27/15 (2006.01)

H01L 25/075 (2006.01)

(52) **U.S. Cl.**

CPC **H01L 33/62** (2013.01); **H01L 25/0753**
(2013.01); **H01L 27/15** (2013.01); **H01L**
33/483 (2013.01)

(58) **Field of Classification Search**

CPC H01L 33/483; H01L 33/62; H01L 27/15;
H01L 25/0753

USPC 257/99
See application file for complete search history.

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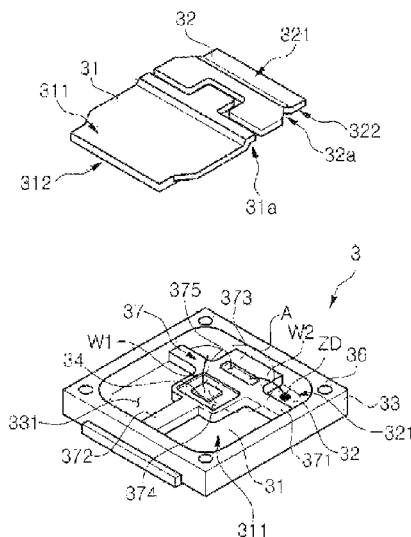
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(57) **ABSTRACT**

A light emitting diode (LED) package includes an LED chip,
a first lead frame and a second lead frame electrically con-
nected to the LED chip and separated by a space, and a
housing disposed on the first lead frame and the second lead
frame. The housing includes an external housing surrounding
a cavity, the cavity exposing a first portion of the first lead
frame and a first portion of the second lead frame, and an
internal housing disposed in the space, the internal housing
covering a top portion of the first lead frame and a top portion
of the second lead frame.

20 Claims, 4 Drawing Sheets



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Fig. 1(a)

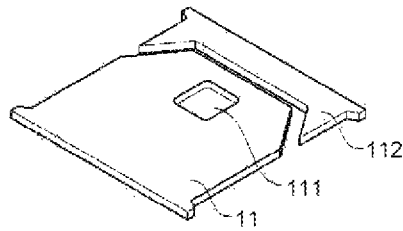


Fig. 1(b)

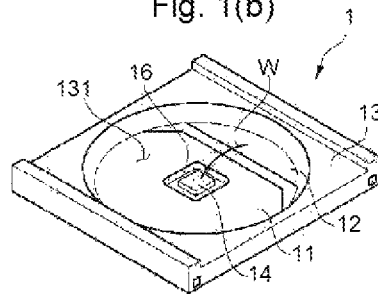


Fig. 1(c)

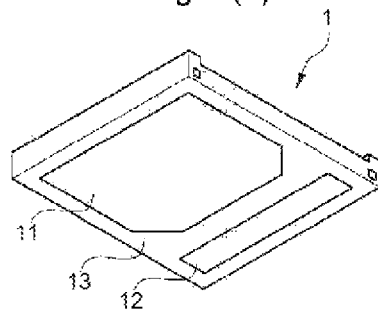


Fig 2(a)

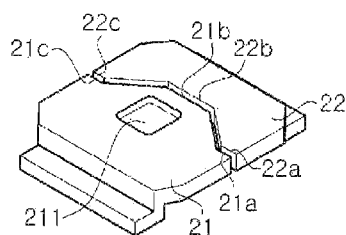


Fig. 2(b)

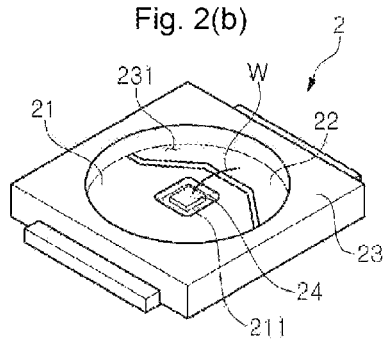


Fig. 2(c)

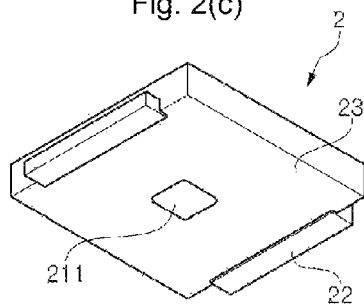


Fig. 3(a)

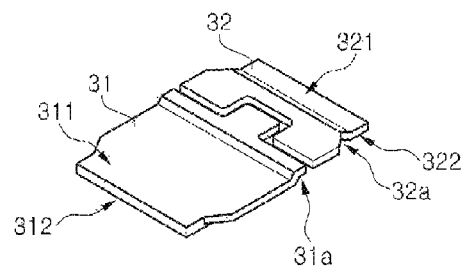


Fig. 3(b)

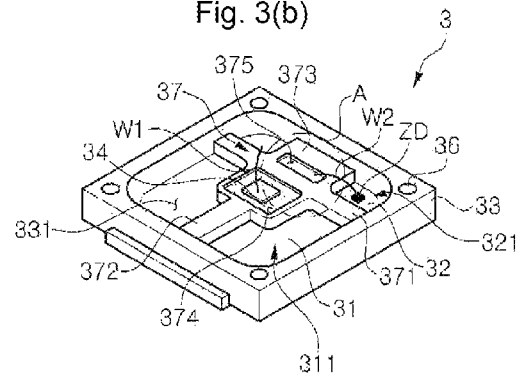


Fig. 3(c)

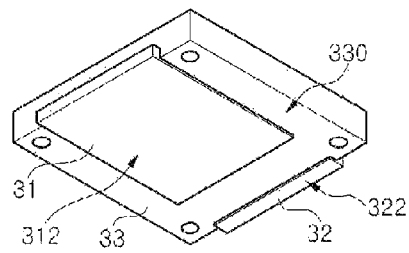
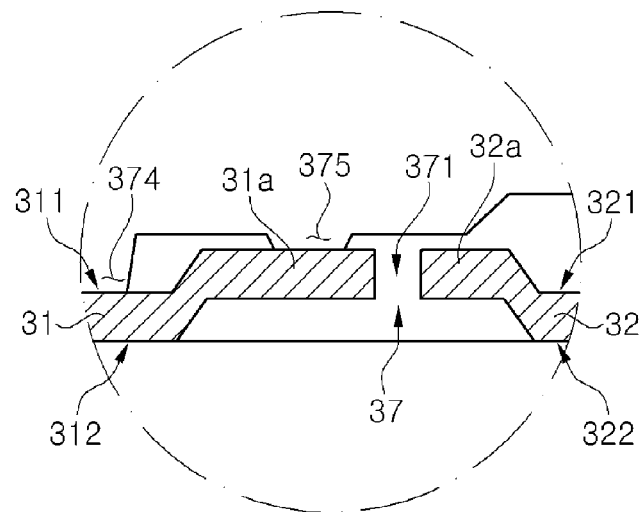


FIG 4



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LIGHT EMITTING DIODE PACKAGE

CROSS-REFERENCE TO RELATED APPLICATIONS

This application is a Continuation of U.S. patent application Ser. No. 14/330,518, filed on Jul. 14, 2014, which is a Continuation of U.S. patent application Ser. No. 13/113,662, filed on May 23, 2011, now issued as U.S. Pat. No. 8,796,710, and claims priority from and the benefit of Korean Patent Application No. 10-2010-0048117, filed on May 24, 2010, which are hereby incorporated by reference for all purposes as if fully set forth herein.

BACKGROUND OF THE INVENTION

1. Field of the Invention

Exemplary embodiments of the present invention relate to a light emitting diode (LED) package and, more particularly, to an LED package which includes a housing configured to surround uplift portions formed on lead frames electrically connected to an LED chip. The LED package is to increase a heat dissipation area while increasing physical strength between the lead frames and preventing moisture absorption.

2. Discussion of the Background

A light emitting diode (LED) is a semiconductor device that emits light through recombination of holes and electrons in a P-N junction between a P-type semiconductor and an N-type semiconductor. Such an LED may be manufactured as a package structure having an LED chip mounted therein.

A conventional LED package **1** includes first and second lead frames **11**, **12** having a direct type heat dissipation structure. As shown in FIG. 1(a), one of the first and second lead frames **11**, **12** separated from each other, for example the first lead frame **11**, is formed with a hole-cup **111** by half-etching.

A housing **13** is formed to support the first and second lead frames **11**, **12**, and an LED chip **14** is mounted on the bottom of the hole-cup **111**. As shown in FIG. 1(b), the housing **13** includes the hole-cup **111** and a cavity **131** which exposes portions of the first and second lead frames **11**, **12**. The housing **13** may be formed by, for example, polyphthalamide (PPA) injection or epoxy molding.

The LED chip **14** mounted in the hole-cup **111** is electrically connected to the second lead frame **12** via a bonding wire **W**. The hole-cup **111** is filled with a light-transmitting resin **16** containing at least one phosphor, and color uniformity of light emitted from the LED chip **14** can be enhanced by the phosphor in the hole-cup **111**. An encapsulation material (not shown) may be disposed in the cavity **131** of the housing **13** to protect the LED chip **14** mounted in the hole-cup **111**.

When electric power is applied to the lead frames **11**, **12** of the LED package **1** from an external power source, the LED chip **14** is driven to emit light to the outside through the encapsulation material. Here, on a lower surface of the LED package shown in FIG. 1(c), the first lead frame **11** having the LED chip **14** mounted thereon and the second lead frame **12** are exposed outside, and may thereby enhance heat dissipation efficiency from the LED chip **14**.

However, although the LED package **1** shown in FIGS. 1(a)-1(c) may have high heat dissipation efficiency, a portion dividing the first and second lead frames **11**, **12** may have low physical strength and may be vulnerable to moisture, and the hole-cup **111** formed by half-etching may be non-uniform, thereby making it difficult to maintain uniformity of light generated from the LED chip **14**. Further, when the hole-cup

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111 is formed by etching, manufacturing costs of the package may increase, thereby limiting mass production.

A conventional LED package **2** developed to solve the problems of such a conventional LED package **1** having low physical strength and vulnerability to moisture includes first and second lead frames **21**, **22** as shown in FIG. 2(a). Specifically, the first lead frame **21** includes a first horizontal section **21a**, a protrusion **21b** bent from the horizontal section **21a** and protruding to a predetermined distance from the first horizontal section **21a**, and a second horizontal section **21c** bent and extending from the protrusion **21b**. Further, the second lead frame **22** includes a third horizontal section **22a** facing the first horizontal section **21a**, a depression **22b** bent from the third horizontal section **22a** and depressed into the second lead frame **22**, and a fourth horizontal section **22c** bent from the depression **22b** and facing the second horizontal section **21c**. The protrusion **21b** of the first lead frame **21** is disposed inside the depression **22b** of the second lead frame **22**.

Referring to FIG. 2(b), the LED package **2** has a housing **23** configured to support the first and second lead frames **21**, **22** and having a cavity **231** exposing an LED chip **24**. A bonding wire **W** and portions of the first and second lead frames **21**, **22** are exposed through the cavity **231**. The cavity **231** may be provided with an encapsulation material (not shown) to encapsulate the LED chip **24**.

The first lead frame **21** includes a down-set portion **211** formed by stamping, and the LED chip **24** is mounted in the down-set portion **211**. The down-set portion **211** is filled with a light-transmitting resin containing at least one phosphor. As shown in FIG. 2(c), a lower surface of the down-set portion **211** is coplanar with a lower surface of the LED package **2**. In FIGS. 2(b)-2(c), the LED package **2** may have low heat dissipation efficiency from the LED chip **24** due to a narrow heat dissipation area, which corresponds to the lower surface of the down-set portion **211**.

SUMMARY OF THE INVENTION

Exemplary embodiments of the invention provide an LED package which includes a housing configured to surround uplift portions formed on lead frames electrically connected to an LED chip. The LED package is to increase a heat dissipation area while increasing physical strength between the lead frames and preventing moisture absorption.

Additional features of the invention will be set forth in the description which follows and in part will be apparent from the description, or may be learned by practice of the invention.

An exemplary embodiment of the present invention discloses an LED package including an LED chip, a first lead frame and a second lead frame electrically connected to the LED chip, the first lead frame and the second lead frame respectively including a first uplift portion and a second uplift portion on facing regions thereof, and a housing supporting the first lead frame and the second lead frame, a first side of the housing exposed to the outside. The first lead frame and the second lead frame each include a first side parallel to the first side of the housing and a second side opposite to the first side.

It is to be understood that both the foregoing general description and the following detailed description are exemplary and explanatory and are intended to provide further explanation of the invention as claimed.

BRIEF DESCRIPTION OF THE DRAWINGS

The accompanying drawings, which are included to provide a further understanding of the invention and are incor-

porated in and constitute a part of this specification, illustrate embodiments of the invention, and together with the description serve to explain the principles of the invention.

FIGS. 1(a), 1(b), 1(c), 2(a), 2(b), and 2(c) illustrate conventional LED packages.

FIGS. 3(a), 3(b), and 3(c) illustrate an LED package according to an exemplary embodiment of the invention.

FIG. 4 is an enlarged cross-sectional view of circle A shown in FIG. 3(b).

DETAILED DESCRIPTION OF THE ILLUSTRATED EMBODIMENTS

The invention is described more fully hereinafter with reference to the accompanying drawings, in which exemplary embodiments of the invention are shown. This invention may, however, be embodied in many different forms and should not be construed as limited to the exemplary embodiments set forth herein. Rather, these exemplary embodiments are provided so that this disclosure is thorough and will fully convey the scope of the invention to those skilled in the art. In the drawings, the sizes and relative sizes of layers and regions may be exaggerated for clarity. Like reference numerals in the drawings denote like elements.

It will be understood that when an element such as a layer, film, region or substrate is referred to as being “on” another element, it can be directly on the other element or intervening elements may also be present. In contrast, when an element is referred to as being “directly on” another element, no intervening elements are present.

FIGS. 3(a) to 3(c) illustrate an LED package according to an exemplary embodiment of the invention, and FIG. 4 is an enlarged cross-sectional view of circle A shown in FIG. 3(b).

According to the present exemplary embodiment, an LED package 3 includes lead frames 31, 32, as shown in FIG. 3(a).

Referring to FIG. 3(a), the lead frames 31, 32 are separated from each other. The lead frames 31, 32 include uplift portions 31a, 32a respectively formed at adjacent portions thereof. The uplift portions 31a, 32a may be formed by stamping a substantially flat metal plate using, for example, a punch, such that portions of the metal plate respectively corresponding to an anode and a cathode are raised relatively higher than the rest of the lead frames 31 and 32.

Further, the lead frames 31, 32 are disposed to face each other. More specifically, a substantially rectangular tab portion of the uplift portion 31a of the first lead frame 31 is disposed in a corresponding substantially rectangular recessed area in the uplift portion 32a of the second lead frame 32 to lengthen a space formed therebetween, as illustrated in FIG. 3(a).

Referring to FIG. 3(b), the LED package 3 according to the present exemplary embodiment includes a housing which supports the first and second lead frames 31, 32 while surrounding the uplift portions 31a, 32a. The housing may be divided into an external housing 33 and an internal housing 37.

The external housing 33 is open at an upper side thereof and includes a cavity 331 for receiving an LED chip 34.

Further, the external housing 33 may be formed thereon with a mounting hole 36 in consideration of mounting a lens part (not shown). The cavity 331 may be provided therein with an encapsulation material (not shown) which entirely encapsulates the internal housing 37. The encapsulation material may be formed of a light-transmitting resin, for example, silicone resin or epoxy resin.

The internal housing 37 is integrally formed with the external housing 33 by injection molding and has a lower height

than the external housing 33. The internal housing 37 and the external housing 33 are configured to expose some of upper surfaces 311, 321 of the first and second lead frames 31, 32. In the present exemplary embodiment, the internal housing 37 is disposed inside the cavity 331 and the external housing 33 is disposed outside the cavity 331, to be connected to the internal housing 37. The external housing 33 and the internal housing 37 may be formed of, for example, PPA or epoxy.

The internal housing 37 includes a reinforcing portion 371, bridges 372, 373, and exposing portions 374, 375, and has a substantially cross shape.

The reinforcing portion 371 fills a space between the first and second lead frames 31, 32, including the lengthened space formed by the substantially rectangular tab and recess portions. In particular, as shown in FIG. 4, the reinforcing portion 371 surrounds the uplift portions 31a, 32a of the first and second lead frames 31, 32, and may be formed higher than the uplift portions 31a, 32a. Since the structure of the reinforcing portion 371 completely surrounds the uplift portions 31a, 32a and the reinforcing portion 371 is formed higher than the uplift portions 31a, 32a, physical strength at a portion dividing the first and second lead frames 31, 32 may be further enhanced and moisture absorption may be prevented.

The bridges 372, 373 extend from the reinforcing portion 371 and are connected to the external housing 33. In the present exemplary embodiment, a first bridge 372 extends from the reinforcing portion 371 to be disposed on a partial region of the first lead frame 31 and is connected to the external housing 33, and a second bridge 373 extends from the reinforcing portion 371 to be disposed on a partial region of the second lead frame 32 and is connected to the external housing 33.

The exposing portions 374, 375 partially expose upper surfaces 311, 321 of the first and second lead frames 31, 32. In the present exemplary embodiment, the first exposing portion 374 exposes a portion of the upper surface 311 of the first lead frame 31 within the first bridge 372 to provide a mounting area for the LED chip 34. The LED chip 34 is mounted on the portion of the upper surface 311 of the first lead frame 31 exposed by the first exposing portion 374. The mounted LED chip 34 is connected to one of exposed portions of the upper surface 321 of the second lead frame 32 via a first bonding wire W1, with the second bridge 373 interposed between the exposed portions of the upper surface 321.

Although the first exposing portion 374 is illustrated as having a rectangle shape with rounded corners in the present exemplary embodiment, the first exposing portion 374 may alternatively have any shape in consideration of the shape and size of the LED chip 34 so long as the LED chip 34 can be mounted at the center of the first exposing portion 374. Further, in addition to the first exposing portion 374, other portions of the upper surface 311 of the first lead frame 31 may be exposed with the first bridge 372 interposed therebetween, and may be used as a mounting area or a bonding area.

The first exposing portion 374 may have an inclined inner wall to reflect light emitted from the LED chip 34. Further, the first exposing portion 374 is provided with an internal encapsulation material (not shown) which covers the LED chip 34 and may be formed of a light-transmitting resin containing at least one phosphor.

The internal housing 37 is formed therein with the second exposing portion 375 through the reinforcing portion 371 and the second bridge 373 to provide a bonding area.

A Zener diode ZD may be mounted on the other exposed portion of the upper surface 321 of the second lead frame 32, with the second bridge 373 interposed between the exposed

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portions of the upper surface **321**, and a second bonding wire **W2** for electrically connecting the Zener diode **ZD** to the first lead frame **31** is bonded to the bonding area provided by the second exposing portion **375**. The Zener diode **ZD** is to protect the LED chip **34** from electrostatic discharge.

The second exposing portion **375** allows the Zener diode **ZD** to be electrically connected to the first and second lead frames **31**, **32** via the second bonding wire **W2** without crossing the first bonding wire **W1**.

Referring to FIG. 3(c), a bottom surface **330** of the LED package **3** includes bottom surfaces of the external housing **33** and the internal housing **37**, and is parallel with lower surfaces **312**, **322** of the first and second lead frames **31**, **32** excluding the uplift portions **31a**, **32a**. The bottom surface **330** of the LED package **3** may be coplanar and flush with lower surfaces **312**, **322** of the first and second lead frames **31**, **32**. Accordingly, heat from the LED chip **34** may be discharged through the lower surfaces **312**, **322** of the first and second lead frames **31**, **32**, thereby improving heat dissipation efficiency from the LED package.

According to the exemplary embodiments of the present invention, the LED package includes a housing configured to surround uplift portions formed on lead frames electrically connected to an LED chip. The LED package is to increase a heat dissipation area while increasing physical strength between the lead frames and preventing moisture absorption. Particularly, a reinforcing portion filling a space between the lead frames may increase physical strength between the lead frames.

Although the invention has been illustrated with reference to some exemplary embodiments in conjunction with the drawings, it will be apparent to those skilled in the art that various modifications and changes can be made to the invention without departing from the spirit and scope of the invention. Further, it should be understood that some features of a certain embodiment may also be applied to other embodiment without departing from the spirit and scope of the invention. Therefore, it should be understood that the embodiments are provided by way of illustration only and are given to provide complete disclosure of the invention and to provide thorough understanding of the invention to those skilled in the art. Thus, it is intended that the invention cover the modifications and variations provided they fall within the scope of the appended claims and their equivalents.

What is claimed is:

1. A light emitting diode (LED) package, comprising:
at least one LED chip;
a first lead frame and a second lead frame electrically connected to the at least one LED chip and separated by a space; and
a housing disposed on the first lead frame and the second lead frame, the housing comprising:
an external housing surrounding a cavity, the cavity exposing a first portion of the first lead frame and a first portion of the second lead frame; and
an internal housing disposed within the cavity, the internal housing comprising a first bridge extending from inner side surfaces of the external housing to intersect the space.
2. The LED package of claim 1, wherein the first bridge divides the first portion of at least one of the first lead frame and the second frame into two portions.
3. The LED package of claim 1, wherein the internal housing is lower than a top surface of the external housing.

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4. The LED package of claim 1, wherein the internal housing further comprises a second bridge disposed in the space.

5. The LED package of claim 4, the second bridge covers portions of a top surface of the first lead frame and a top surface of the second lead frame.

6. The LED package of claim 1, wherein each of the first lead frame and the second frame comprises a side portion and a bottom portion exposed from the housing.

7. The LED package of claim 6, wherein the bottom portion is coplanar and flush with the bottom surface of the housing.

8. The LED package of claim 1, further comprising a Zener diode disposed on the second lead frame.

9. The LED package of claim 1, wherein the internal housing comprises an inclined surface.

10. The LED package of claim 1, wherein the at least one LED chip is disposed on the first lead frame and connected to the second lead frame by a wire.

11. The LED package of claim 10, wherein the wire overlaps a portion of the internal housing.

12. The LED package of claim 1, wherein the first lead frame comprises a substantially rectangular tab and the second lead frame comprises a corresponding substantially rectangular recess forming a lengthened space between side surfaces of the first and second lead frames to increase a mechanical bonding strength with the housing.

13. A light emitting diode (LED) package, comprising:

at least one LED chip;

a first lead frame and a second lead frame electrically connected to the at least one LED chip and separated by a space; and

a housing disposed on the first lead frame and the second lead frame, the housing comprising:

an external housing surrounding a cavity, the cavity exposing a first portion of the first lead frame and a first portion of the second lead frame; and

an internal housing disposed within the cavity, the internal housing dividing the first portion of at least one of the first lead frame and the second lead frame into two portions.

14. The LED package of claim 13, wherein the internal housing comprises a first bridge extending from inner side surfaces of the external housing to intersect the space.

15. The LED package of claim 13, wherein the internal housing is lower than a top surface of the external housing.

16. The LED package of claim 13, wherein the internal housing further comprises a second bridge disposed in the space.

17. The LED package of claim 13, wherein each of the first lead frame and the second lead frame comprise a side portion and a bottom portion exposed from the housing.

18. The LED package of claim 17, wherein the bottom portion is coplanar and flush with the bottom surface of the housing.

19. The LED package of claim 13, wherein the at least one LED chip is disposed on the first lead frame and connected to the second lead frame by a wire.

20. The LED package of claim 19, wherein the wire overlaps a portion of the internal housing.

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